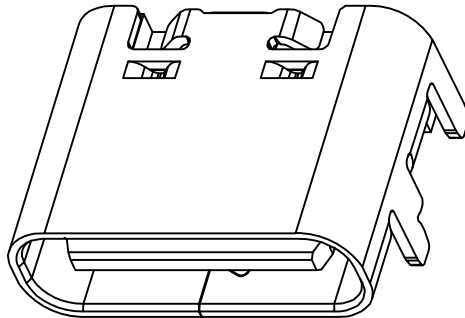
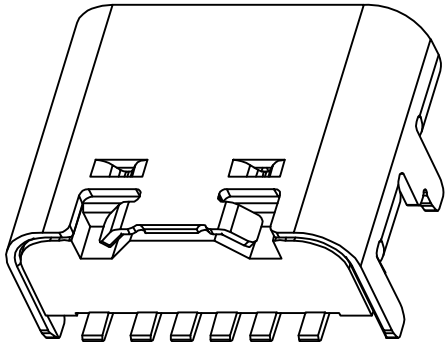
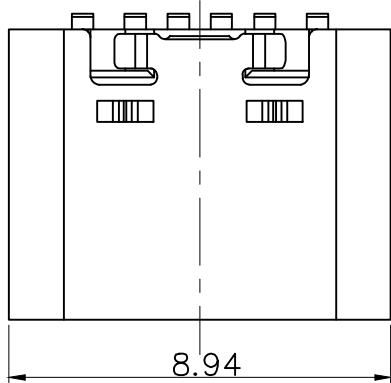


标 记 MARK	ECN编号/变更内容 ECN NO/DEFINITION	修 改 REVISE	日 期 DATE	核 准 APPROVE
A5	CC1	B12	GND	
A9	VBUS	B9	VBUS	
		B5	CC2	
		B1	GND	
PIN	SIGNAL NAME	PIN	SIGNAL NAME	



NOTE:

1.MATERIAL SPECIFICATION:

1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC.

2.CONTACTS:COPPER ALLOY

3.MID PLATE: STAINLESS STEEL

4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

Ni 50u" MIN. UNDER PLATED OVER ALL.

Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

SEE TABLE1.

2-3.SHIELD PLATE&EMI PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

3-1.INSERTION FORCE: 0.5~2.0kgf.

3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.

3-3.DURABILITY: 5000 CYCLES.

4.ELECTRICAL PERFORMANCE,

4-1. CURRENT RATING:3.0A

VOLTAGE RATING:5.0V

4-2. LLCR:

VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.

SHIELD: 50mΩ/MAX.

LLCR MAX. CHANGE OF ALL PINS: 10mΩ.

4-3.INSULATION RESISTANCE: 100MΩ MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

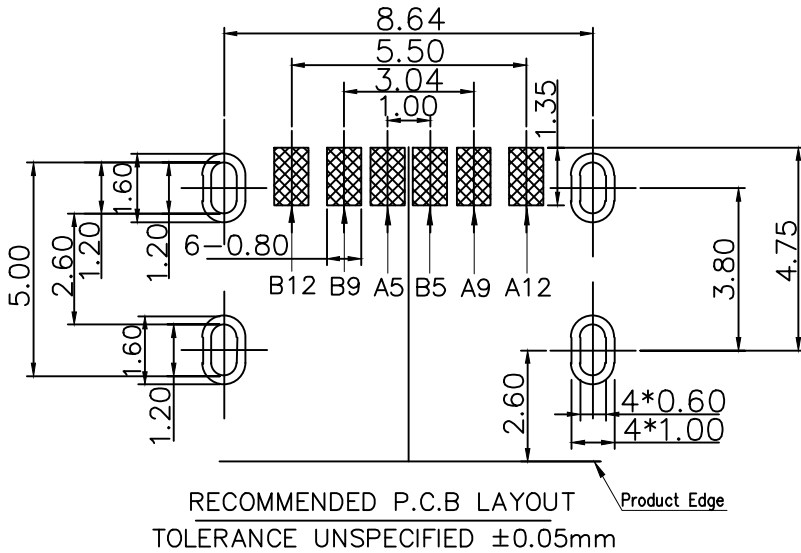
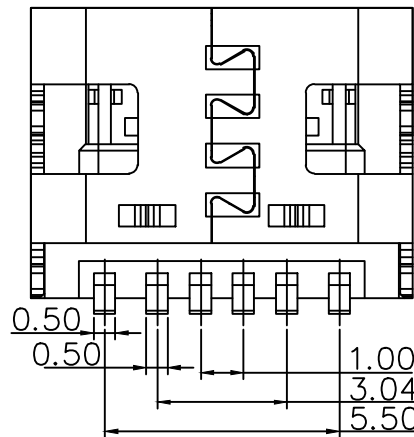
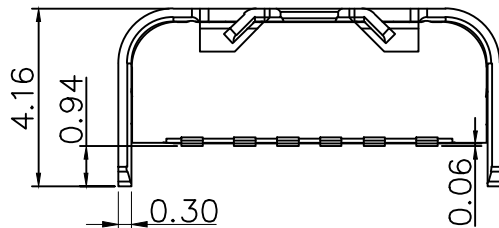
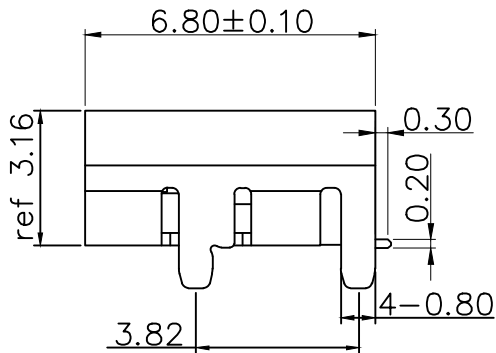
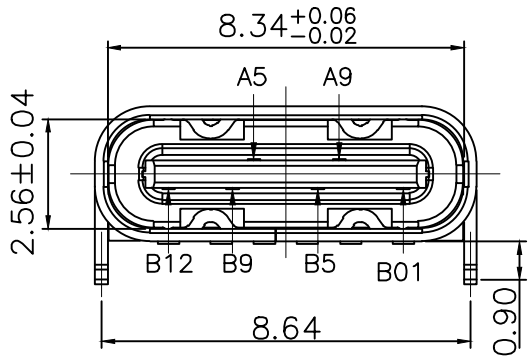
5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°C~+85°C.

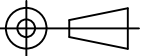
6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL

BE MAINTAINED FOR 10 SECONDS AT 260°C.



3	外壳	不锈钢	镀镍	
2	接触	铜	镀金	
1	基座	LCP	黑色	
序 号	品 名	材 质	电镀/颜色	备 注

 深圳市虹成电子有限公司		品 名 TITLE	TYPE-C母座	
		料 号 PART NO	HC-TYPE-C-6P-010C	
GENERAL TOLERANCES (UNLESS SPECIFIED)		比 列 SCALE	1:1	
X.X	±0.30	X.°	±10°	制 图 DRAW
.XX	±0.20	.X°	±8°	审 核 CHECKED
.XXX	±0.10	.XX°	±5°	批 准 APPROVE
		单 位 UNIT	MM	AhYe
		张 数 PART NO	1 OF 1	夏操云
		版 本 REV	A	赵亮亮

